

Title (en)

ELECTRONIC CIRCUIT ARRANGEMENT AND METHOD FOR PRODUCING AN ELECTRONIC CIRCUIT ARRANGEMENT

Title (de)

ELEKTRONISCHE SCHALTUNGSANORDNUNG UND VERFAHREN ZUR HERSTELLUNG EINER ELEKTRONISCHEN SCHALTUNGSANORDNUNG

Title (fr)

STRUCTURE DE COMMUTATION ÉLECTRONIQUE ET PROCÉDÉ DE FABRICATION D'UNE STRUCTURE DE COMMUTATION ÉLECTRONIQUE

Publication

EP 1946625 A1 20080723 (DE)

Application

EP 06807009 A 20061005

Priority

- EP 2006067101 W 20061005
- DE 102005053974 A 20051111

Abstract (en)

[origin: DE102005053974B3] An electronic circuit comprises a heat sink (12) thermally coupled to a circuit carrier (16) for wiring electronic components (20,22). A second circuit carrier (18) in a recess (24) in the first has top surface interconnections to the first carrier (26,28,30) and an electrical component (34) between the second carrier and the heat sink is electrically connected to the second carrier and thermally coupled to the heat sink. An independent claim is also included for a production process for the above.

IPC 8 full level

H05K 1/02 (2006.01); **H05K 1/14** (2006.01); **H05K 7/20** (2006.01)

CPC (source: EP US)

H01L 23/36 (2013.01 - EP US); **H01L 25/162** (2013.01 - EP US); **H05K 1/021** (2013.01 - EP US); **H05K 1/142** (2013.01 - EP US); **H01L 24/48** (2013.01 - EP US); **H01L 24/49** (2013.01 - EP US); **H01L 2224/05554** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/48137** (2013.01 - EP US); **H01L 2224/49175** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US); **H01L 2924/01079** (2013.01 - EP US); **H01L 2924/09701** (2013.01 - EP US); **H01L 2924/14** (2013.01 - EP US); **H05K 1/141** (2013.01 - EP US); **H05K 1/182** (2013.01 - EP US); **H05K 3/0061** (2013.01 - EP US); **H05K 2201/1056** (2013.01 - EP US); **H05K 2201/10674** (2013.01 - EP US); **H05K 2203/049** (2013.01 - EP US); **Y10T 29/49124** (2015.01 - EP US)

C-Set (source: EP US)

1. **H01L 2224/48091 + H01L 2924/00014**
2. **H01L 2924/14 + H01L 2924/00**
3. **H01L 2924/00014 + H01L 2224/45099**
4. **H01L 2924/00014 + H01L 2224/45015 + H01L 2924/207**

Citation (examination)

- DE 19859739 A1 20000706 - BOSCH GMBH ROBERT [DE]
- DE 4030532 A1 19920402 - BOSCH GMBH ROBERT [DE]
- US 5297006 A 19940322 - MIZUKOSHI MASATAKA [JP]
- US 4879630 A 19891107 - BOUCARD MICHEL [FR], et al
- DE 4129835 A1 19930311 - BOSCH GMBH ROBERT [DE]

Designated contracting state (EPC)

DE FR IT

DOCDB simple family (publication)

DE 102005053974 B3 20070301; CN 101356862 A 20090128; CN 101356862 B 20101117; EP 1946625 A1 20080723; US 2009161319 A1 20090625; US 7911051 B2 20110322; WO 2007054409 A1 20070518

DOCDB simple family (application)

DE 102005053974 A 20051111; CN 200680050898 A 20061005; EP 06807009 A 20061005; EP 2006067101 W 20061005; US 9333206 A 20061005